



In re the Application of: **HOSHI, Kenji et al.**

Group Art Unit: **2814**

Serial No.: 10/073,314

Examiner: **TRINH, HOA B.**

Filed: **February 13, 2002**

**P.T.O. Confirmation No.: 4466**

For: **SEMICONDUCTOR DEVICE AND ALIGNMENT SENSING  
METHOD FOR SEMICONDUCTOR DEVICE**

**AMENDMENT UNDER 37 CFR §1.111**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

RECEIVED  
JUN 10 2003  
TECHNICAL SERVICES SECTION 2800  
May 30, 2003

Sir:

In response to the Office Action dated **March 5, 2003**, please amend the above-identified application as follows:

**IN THE CLAIMS:**

1. (Amended) A semiconductor device comprising a plurality of alignment marks formed over a semiconductor wafer,

each of the alignment marks being divided by a micronized pattern,

the micronized pattern having a size smaller than a resolution limit of an alignment sensor,

and

the micronized pattern having a pattern forming margin larger than that of a device pattern  
formed over the semiconductor wafer has.